



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM  $\text{C}$ .
4. PRIMARY DATUM  $\text{C}$  AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. JEDEC REFERENCE: JEP95 DG4.18
- \* VALUES ARE BASED ON SUBCON CAPABILITY

|                            | SYMBOL | COMMON DIMENSIONS |        |       |
|----------------------------|--------|-------------------|--------|-------|
|                            |        | MIN.              | NOM.   | MAX.  |
| Total Thickness            | A      | 0.760             | 0.800  | 0.840 |
| Stand Off                  | A1     | 0.206             | 0.236  | 0.266 |
| Wafer Thickness            | A2     | 0.564             | ±0.025 |       |
| Backside Coating Thickness | A3     | —                 |        |       |
| Si Die Thickness           |        | 0.531             | REF    |       |
| Body Size                  | D      | 9.000             | BSC    |       |
|                            | E      | 11.000            | BSC    |       |
| Ball Diameter (Size)       |        | 0.300             |        |       |
| Ball/Bump Width            | b      | 0.289             | 0.319  | 0.349 |
| Ball/Bump Pitch            | eD     | 0.500             |        |       |
|                            | eE     | 0.500             |        |       |
| Ball/Bump Count            | n      | 410               |        |       |
| Edge Ball Center to Center | D1     | 8.227             | BSC    |       |
|                            | E1     | 10.000            | BSC    |       |
| Package Edge Tolerance     | aaa    | 0.030             |        |       |
| Coplanarity (whole wafer)  | ddd    | 0.050             |        |       |
| Ball/Bump Offset (Package) | *eee   | 0.060             |        |       |
| Ball/Bump Offset (Ball)    | *fff   | 0.030             |        |       |

Title: Package Outline Drawing

Pkg Type: FOWLP

Document No:

Product Family: LAV-AT

Pin Count: 410

POD-240094

Product Name: LAV-AT-E30B-ASGA410

Pkg Size: 9x11 mm

Rev: B

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